Quantitative Imaging of Sheet Resistance with a Scanning Near-Field Microwave Microscope

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We describe quantitative imaging of the sheet resistance of metallic thin $\,$ lm s by monitoring frequency shift and quality factor in a resonant scanning near-eld microwave microscope. This technique allows fast acquisition of images at approximately 10 ms per pixel over a frequency range from 0.1 to 50 GHz. In its current conguration, the system can resolve changes in sheet resistance as small as 0.6 = 2 for 100 = 2 $\,$ lm s. We demonstrate its use at 7.5 GHz by generating a quantitative sheet resistance image of a YB a₂C u₃O $_7$ thin $\,$ lm on a 5 cm -diameter sapphire wafer.

Non-destructive in aging of microwave sheet resistance has been demonstrated using a variety of probes combined with resonant systems. Fare eld techniques, such as confocal i^2 and dielectric i^3 resonators, while allowing quantitative sheet resistance in aging, have the disadvantage of relatively low spatial resolution (i1 mm) limited by the wavelength. Neared microscopy using coaxial i^5 , if microstrip, or waveguide resonators, or each higher spatial resolution. However, current techniques either require contact with the sample, inhibiting quantitative interpretation of the data, have low sheet resistance sensitivity in conducting samples, i^5 , or require additional in age processing to obtain subwavelength resolution. For non-destructive sheet resistance in aging of thin length is desirable to have quantitative methods that combine high resolution, high speed, simple construction from commercially-available components, and straightforward in age interpretation. We describe here the application of an open-ended coaxial probe resonator to obtain quantitative in ages of microwave sheet resistance with /80 spatial resolution.

Our scanning m icrow ave m icroscope consists of a resonant coaxial transm ission line connected to an open-ended coaxial probe and a m icrow ave source (Fig. 1). 10 The m icrow ave source, which is weakly coupled to the resonant transm ission line through a decoupling capacitor C_D , is frequency modulated by an external oscillator at a rate f_{FM} 3 kHz. The electric eld at the probe tip is perturbed by the region of the sample beneath the probe's center conductor. We monitor these perturbations using a diode detector which produces a voltage signal proportional to the power rejected from the resonator. A feedback circuit (Fig. 1) keeps the microw ave source locked to a resonant frequency of the transm ission line, and has a voltage output which is proportional to shifts in the resonant frequency due to the sample.

To determ ine the relationship between Q_0 and sample sheet resistance (R_X), we used a variable-thickness alum inum thin Im on a glass substrate. The cross-section of the thin Im is wedge-shaped, in plying a spatially varying sheet resistance. Using a probe with a 500 m diameter center conductor, and selecting a resonance of the microscope with a frequency of 7.5 GHz, we acquired frequency-shift and Q_0 data. We then cut the sample into narrow strips to take two-point resistance measurements and determine the local sheet resistance. The unloaded Q_0 of the resonator as a function of R_X is shown in Fig. 2 for various probe-sample separations. We note that Q_0 reaches a maximum as R_X ! 0; as R_X increases, Q_0 drops due to loss from currents induced in the sample, reaching a minimum around R_X = 660 =2 for a height of 50 m. Similarly, as R_X ! 1, Q_0 increases due to diminishing currents in the sample.

a) Electronic mail: steinhau@squid.umd.edu. Color versions of the gures in this paper can be found at http://www.csr.umd.edu/research/hifreq/micr_microscopy.html.

We also note that when the probe is located 50 m above the bare glass substrate, Q $_0$ = 549, which is only slightly less than Q 0 = 555 when the probe is far away (> 1 mm) from the sample. Using $1=Q_0=1=Q_s+1=Q^0$, we not Q $_s$ = 51000 Q 0 = 555, where Q $_s$ is associated with losses in the glass substrate, and Q 0 is associated with losses in the transm ission line. As a result, we conclude that the glass substrate has little election Q $_0$. In contrast, because the dielectric substrate electively lengthens the microscope resonant circuit, frequency shift is highly sensitive to the substrate. This suggests that we use the Q data, rather than the frequency shift data, to generate substrate-independent in ages of thin lim sheet resistance.

As shown in Fig.2, R_X is a double-valued function of Q_0 . This presents a problem for converting the m easured Q_0 to R_X . However, R_X is a single-valued function of the frequency shift, allowing one to use the frequency shift data to determ ine which branch of the R_X (Q) curve should be used.

To better understand the system's behavior, we modeled the interaction between the probe and sample as a capacitance C_X between the probe's center conductor and the sample in series with the sample sheet resistance R_X (see Fig. 1). $^{12;16}$ W e assumed a parallel plate approximation for the capacitor C_X , and took $R_X = \sim t$, where \sim is the sample do resistivity, and t is the limit thickness. To ind Q, we calculated the width of the resonant minimum in the rejection occions j^2 vs. frequency curve, as described above. The model results for a height of 50 mare indicated by the solid line in Fig. 2. To the data we used the measured $Q_0 = 555$ and $Q_L = 353$ with the probe far away from the sample to x two thing parameters: the coupling capacitance $G_0 = 0.17$ pF, and the transmission line attenuation constant = 1.26 dB/m (in close agreement with the manufacturer's specified value of = 1.23 dB/m). A side from a coupling factor involving C_X , the model agrees qualitatively and predicts the = 1.23 dB/m in in manufacturer. For large = 1.23 the model predicts a faster return to the asymptotic = 1.23 value of 555. The overall behavior of this simple model conmand of the system.

To explore the capabilities of our system, we scanned a thin lm of YBa2Cu3O7 (YBCO) on a 5 cm-diam eter sapphire substrate at room temperature. The lm was deposited using pulsed laser deposition with the sample temperature controlled by radiant heating. The sample was rotated about its center during deposition, with the 3 cm diam eterplume held at a position halfway between the center and the edge. The thickness of the YBCO thin lm varied from about 100 nm at the edge to 200 nm near the center.

Figure 3 shows three m icrow ave in ages of the YBCO sample. The frequency shift \mathbb{F} ig. 3(a)] and \mathbb{Q}_0 \mathbb{F} ig. 3(b)] were acquired simultaneously, using a probe with a 500 m-diameter center conductor at a height of 50 m above the sample. The scan took approximately 10 m inutes to complete, with raster lines 0.5 mm apart. The frequency shifts in Fig. 3(a) are relative to the resonant frequency of 7.5 GHz when the probe was far away (>1 mm) from the sample; the resonant frequency shifted downward by more than 2.2 MHz when the probe was above the center of the sample. Noting that the resonant frequency drops monotonically between the edge and the center of the lm, and that the resonant frequency is a monotonically increasing function of sheet resistance, we conclude that the sheet resistance decreases monotonically between the edge and the center.

The frequency shift and Q_0 im ages [Fig. 3] (a) and (b) di er slightly in the shape of the contour lines. This is most likely due to the 300 m—thick substrate being warped, causing a variation of a few m icrons in the probe-sam ple separation during the scan. However, for a sam ple such as that shown in [Fig. 3], with an $[R]_X$ variation across the sam ple of $[R]_X$ the $[R]_X$ data are primarily sensitive to changes in $[R]_X$, while the frequency shift data are primarily sensitive to changes in probe-sam ple separation. As a result, we attribute the dierence between the frequency shift and $[R]_X$ in ages to small changes in probe-sam ple separation, which will mainly a ect the frequency shift data. Since the values of $[R]_X$ are retrieved from the $[R]_X$ data, the warping does not a ect the nal $[R]_X$ appreciably. In principle, one can use the combined frequency shift and $[R]_X$ in ages to extract sample topography information, allowing one to separate the elects of sample sheet resistance and topography.

From Fig. 3(b), we see that the lowest Q occurs near the edge of the lm, and that the Q rises toward the center of the sample. As mentioned above, R_X is not a single-valued function of Q and we must use the frequency shift in age [Fig. 3(a)] to determ ine which branch of the Q_0 vs. R_X curve in Fig. 2 to use. From the frequency shift in age we learned that R_X decreases monotonically from the edge to the center of the sample; therefore we use the branch of the Q_0 vs. R_X curve with R_X < 660 =2, since this is the branch that yields a decreasing R_X for increasing Q_0 .

W ith the appropriate branch identi ed, we then transform ed the Q in age in Fig. 3 (b) to the sheet resistance in age in Fig. 3 (c) using a polynom ial least-squares to the data presented in Fig. 2 for $R_{\rm K}$ < 540 =2 and a height of 50 m . Figure 3 (c) con mm s that the lim does indeed have a lower resistance near the center, as was intended when the lim was deposited. We note that the sheet resistance does not have a simple radial dependence, due to either non-stoichiom etry or defects in the lim .

A fler scanning the YBCO Im, we patterned it and made four-point dc resistance measurements allover the wafer. The dc sheet resistance had a spatial dependence identical to the microwave data in Fig. 3 (c). However, the absolute values were approximately twice as large as the microwave results, most likely due to degradation of the Im during patterning.

To estimate the sheet resistance sensitivity, we monitored the noise in $V_{2f_{FM}}$. We mode the Q sensitivity of the

system to be Q_0 0.08 for Q_0 = 555 and an averaging time of 10 ms. Combining this with the data in Fig. 2, we not $R_X = R_X = 6.4$ 10 3 , for $R_X = 100$ =2 using a probe with a 500 m diameter center conductor at a height of 50 m and a frequency of 7.5 GHz. The sensitivity scales with the capacitance between the probe center conductor and the sample (C_X); increasing the diameter of the probe center conductor and/or decreasing the probe-sample separation would in prove the sensitivity.

In conclusion, we have demonstrated a technique which uses a near-eld microw ave microscope to generate quantitative sheet resistance images of thin lm samples. The strengths of our system include the ability to arrive at quantitative results and to con rm our understanding of the system with a simple model. O ther advantages include its speed, measurement frequency bandwidth, construction from standard commercially-available components, and the possibility of enhancing its spatial resolution by using a probe with a smaller-diameter center conductor. In

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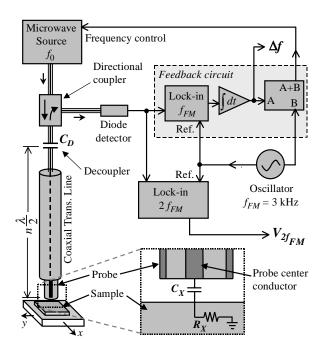


FIG .1. Schem atic of the scanning near—eld m icrow ave m icroscope. The inset shows the interaction between the probe and the sample, represented by a capacitance C_X and a resistance R_X .

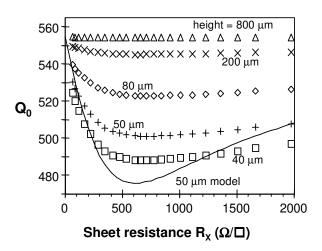


FIG.2. Unloaded quality factor Q_0 of the resonant circuit as a function of the sheet resistance R_X of a variable-thickness alum inum thin—lm sample. The labels indicate di erent probe-sample separations. A probe with a 500 m center conductor was used at a frequency of 7.5 GHz. The solid line indicates a model calculation for a probe-sample separation of 50 m.

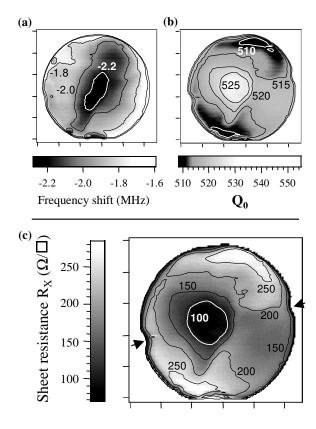


FIG .3. Im ages of a variable-thickness YBCO thin-lm on a 5 cm -diam eter sapphire wafer, where the lm is the thickest at the center. The tick marks are 1 cm apart for the images of (a) frequency shift relative to the resonant frequency when the probe is far away (> 1 mm) from the sample, (b) unloaded Q, and (c) sheet resistance (R_X). The arrows in (c) point to small semi-circular regions where clips held the wafer during deposition, and thus no lm is present. The labels indicate values at each contour line. A probe with a 500 m diam eter center conductor was used at a height of 50 m, at a frequency of 7.5 GHz.

